SPECIFICATIONS FOR HIGH CONDUCTANCE THERMAL INTERFACE MATERIAL

The following are the specifications for “High Conductance Thermal Interface Material” for thermal management of high heat dissipating spacecraft electronics:

Sl. No.	Parameter	Specification
1.	Material	High Conductance Thermal Interface Material
2.	Approx. Size (mm)	~180 × 180
3.	Thickness (mm)	0.350 ± 0.015
4.	Density (kg/m^3)	≤ 2500
5.	In-plane thermal conductivity (W/m°C) @ RT	≥ 200
6.	Across-plane thermal conductivity (W/m°C) @ RT	≥ 25
7.	Compressibility (%) @ 600kPa	≥ 50
8.	Thermal conductance (W/m^2°C) @ 200kPa	≥ 20000
9.	Working temperature (°C)	-50 to +250
10.	Withstand Temperature (°C)	≥ 350
11.	Quantity (Number of sheets)	110